

FIGS. 2(a) and 2(b) presents top views of the structure adopted in the semiconductor device achieved in a second embodiment;

FIGS. 3(a) and 3(b) presents top views of the structure adopted in the semiconductor device achieved in a third embodiment;

FIGS. 4(a) and 4(b) presents top views of the structure adopted in the semiconductor device achieved in a fourth embodiment;

FIGS. 5(a) and 5(b) presents top views of the structure adopted in the semiconductor device achieved in a fifth embodiment;

FIGS. 6(a) and 6(b) presents top views of the structure adopted in the semiconductor device achieved in a sixth embodiment;

a1 FIGS. 7(a) and 7(b) illustrates the structure of the semiconductor device in the sixth embodiment;

FIGS. 8(a) and 8(b) presents top views of the structure adopted in the semiconductor device achieved in a seventh embodiment;

FIGS. 9(a) and 9(b) presents top views of the structure adopted in the semiconductor device achieved in an eighth embodiment; and

FIGS. 10(a) and 10(b) presents top views of the structure adopted in the semiconductor device in the related art.--

Page 22, line 24, through Page 23, line 7, please replace the current paragraph with the following replacement paragraph:

a2 --In addition, as shown in FIG. 9(b), a semiconductor element 702 is mounted at a specific position near the center of the surface of the substrate 701 constituting the

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semiconductor device main body by using the cross mark 703 and a frame portion 708 for reference and is secured with, for instance, an adhesive achieving a higher degree of accuracy. Electrode portions 704 at the mounted semiconductor element 702 are electrically connected to pad electrodes 705 on the substrate 701 constituting the semiconductor device main body via wirings 706a and 706b. As in the semiconductor device in the related art, a specific area containing the semiconductor element 702 on the semiconductor substrate 701 is sealed with resin (not shown) and ball electrodes (not shown) which may be constituted of solder are formed at specific positions at the lower surface of the semiconductor device substrate 701.--

Page 24, line 12, through line 23, please replace the current paragraph with the following replacement paragraph:

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--Next, the electrode portions 704 at the semiconductor element 702 accurately secured onto the semiconductor substrate 701 are electrically connected to the pad electrodes 705 on the substrate 701 at the semiconductor device main body through the wirings 706a and 706b which may be, for instance, gold wires. Subsequently, the specific area on the semiconductor substrate 701 containing the semiconductor element 702 and the pad electrodes at the periphery of the substrate is sealed with resin (not shown) as in the semiconductor device in the related art. In addition, the ball electrodes (not shown) which may be constituted of solder are formed at specific positions at the lower surface of the semiconductor substrate 701, thereby completing the process of manufacturing the semiconductor device in the embodiment.--
